



Hotplate HP-300-Z
Ultra high precision
soft & hard baking



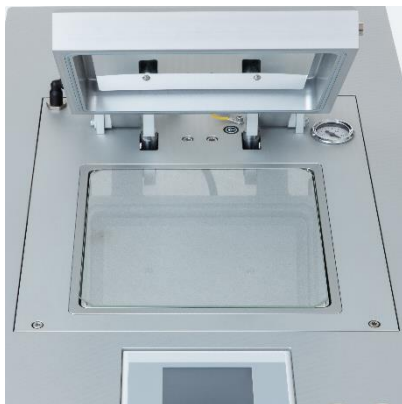
The **Hotplate HP-300-Z** was developed for precise soft bake and hard bake processes in lithography, in MEMS and similar applications. The temperature range is designed for up to 300°C by default. The set temperature and the temperature profile have narrow margins, meaning that a high coating quality can be achieved. The HP series is convincing due to its high level of uniformity and the high-precision process repeatability. It can be used for substrates with a diameter of up to 300mm and thicknesses of 20mm at maximum. The hotplate comes as standard with proximity and loading pins, allowing simultaneous processing of five substrates (up to 100mm).

The **multi-zone heating system** ensures very high temperature distribution, which is adjustable for each zone. The hotplate is covered with safety glass, which makes cleaning easier. Due to the high quality, robust design and easy handling, SAWATEC hotplates are preferentially used for laboratories, R&D, pilot projects and institutes.

The high-precision instrument is available as mobile cabinet unit.

FEATURES (BASIC CONFIGURATION)

- Temperature control with digital target and actual value display
- Quick start function for repeat processes
- Automatic temperature limit switch, no overheating
- Heating ramp up possible with 20 program-steps
- Proximity as well as loading pins, can be easily adapted to different substrate sizes
- Free programmable heating curve with max. 10°C/min (25°-300°C)
- Free programmable cooling curve with max. 5°C/min (300°-40°C)
- Hotplate with multi-zone heating (16 zones) and with safety glass, easy cleaning
- Easy levelling of the hotplate, prevents discharge of photoresist
- User-friendly process configuration with touch screen panel
- Manual substrate fixation via vacuum
- Manual loading and unloading of the substrates



Safety glass



Multi-zone heating for 5x100mm substrates

PERFORMANCE DATA

- Temperature range: ambient temperature up to 300°C
- Temperature accuracy: +/- 0.5°C at 100°C
- Electrical driven proximity and loading pins (stroke 8mm)
- Program controlled adjustable proximity pins (0.1mm increments)

ADDITIONAL FUNCTIONS (OPTIONS)

- N2 flushing program controlled, no oxidation
- HMDS priming program controlled, optimized adhesion
- Simple setup tool for optimal alignment of the hotplate



Lid with N2 flushing, quick start function

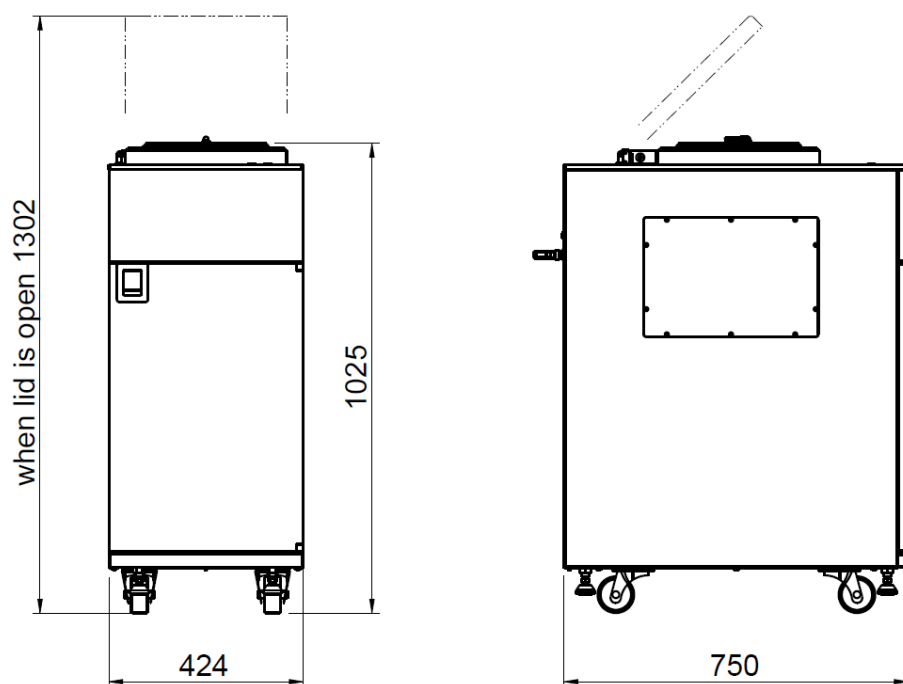


Alignment tool

DESIGN AND DIMENSIONS

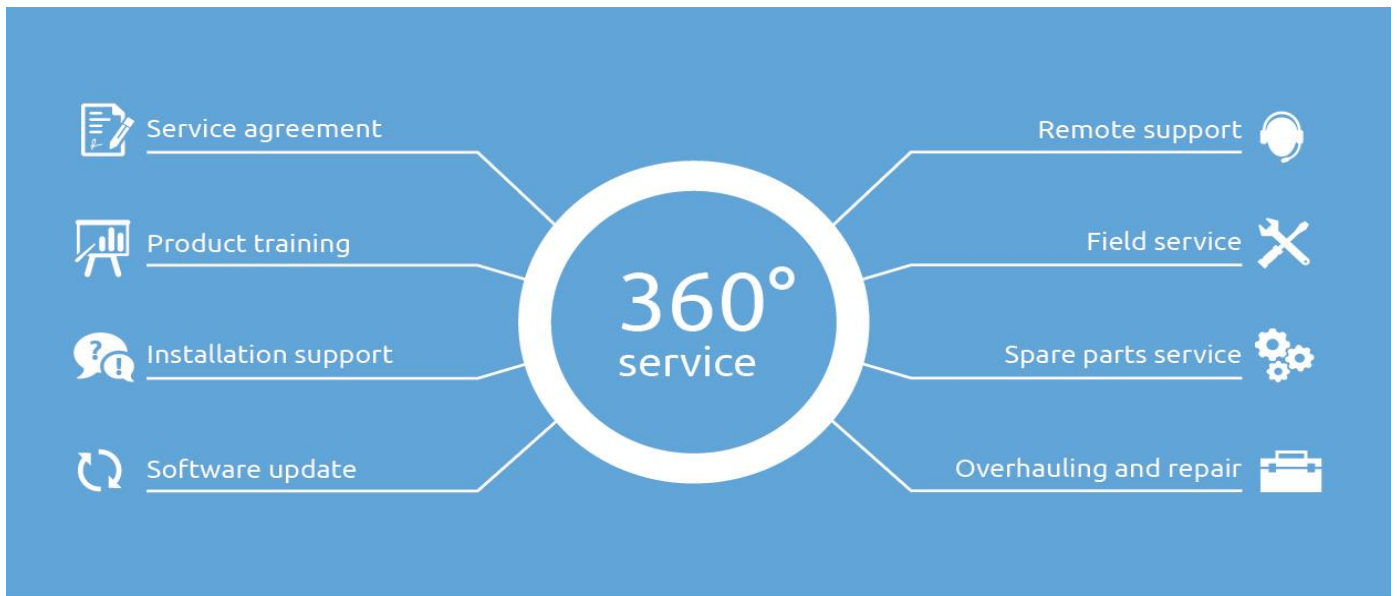
- Compact, space-saving design
- 3.5" colour display touch screen panel
- Hotplate: 320 x 320mm, anodised aluminium
- Lid: open and close with pneumatic lift, anodised aluminium

Mobile cabinet HP-300-Z Cab	
▪	Mobile cabinet made of electro polished stainless steel
▪	Dimensions (lid open): 424 x 750 x 1302mm (L x W x H)
▪	Weight: approx. 80kg



REQUIRED MEDIA

- 3 x 400 VAC 50/60Hz (8kW)
- Technical vacuum, tube Ø6/4mm (-0.8bar)
- Compressed air 4 bar, tube Ø6/4mm
- Cooling water 3l/min at 18°C
- Cooling water In/Out, tube Ø8/6mm (2pcs.)
- Cabinet exhaust-connector Ø 76mm



If you would like a personal consultation or have a specific request, please do not hesitate to call us. Our technical experts will be pleased to help you.

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